



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-09-03
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T835H-6T	7BVP*086SBM1	A	SHENZHEN B/E	2015-09-03
Amount		UoM	Unit type	ST ECOPACK Grade
1900.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	10.2, 15.5, 4.5	3	THROUGH HOLE
Comment	Package: TO 220 NI CLIP		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-l	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	78VP*0865BM1									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	5.807	mg	supplier	die	Silicon (Si)	7440-21-3		5.033	mg	866713	2649				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.101	mg	17393	53				
				supplier	metallization	Gold (Au)	7440-57-5		0.019	mg	3272	10				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	4994	15				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1033	3				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.137	mg	23592	72				
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.041	mg	7060	22				
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.441	mg	75943	232				
				Leadframe	Copper & its alloys	1253.004	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.751	mg	999000	658816
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		1.253	mg	1000	659
JIG - R	solder	Lead (Pb)	7439-92-1					7a-Lead in high me	5.107	mg	925014	2688				
Soft solder	Solder	5.521	mg	supplier	solder	Silver (Ag)	7440-22-4		0.276	mg	49991	145				
				supplier	solder	Tin (Sn)	7440-31-5		0.138	mg	24995	73				
				supplier	mold compound	Silica, vitreous	60676-86-0		454.238	mg	760001	239073				
Encapsulation	Other Organic Materials	597.681	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		60.963	mg	101999	32086				
				supplier	mold compound	Phenol resin	9003-35-4		35.861	mg	60000	18874				
				supplier	mold compound	Others	Proprietary		29.884	mg	50000	15728				
				supplier	mold compound	Metal hydroxide	21645-51-2		11.954	mg	20001	6292				
				supplier	mold compound	Carbon black	1333-86-4		4.781	mg	7999	2516				
				connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348
clip		31.625	mg	supplier	alloy	Copper ( Cu)	7440-50-8		31.625	mg	1000000	16645				